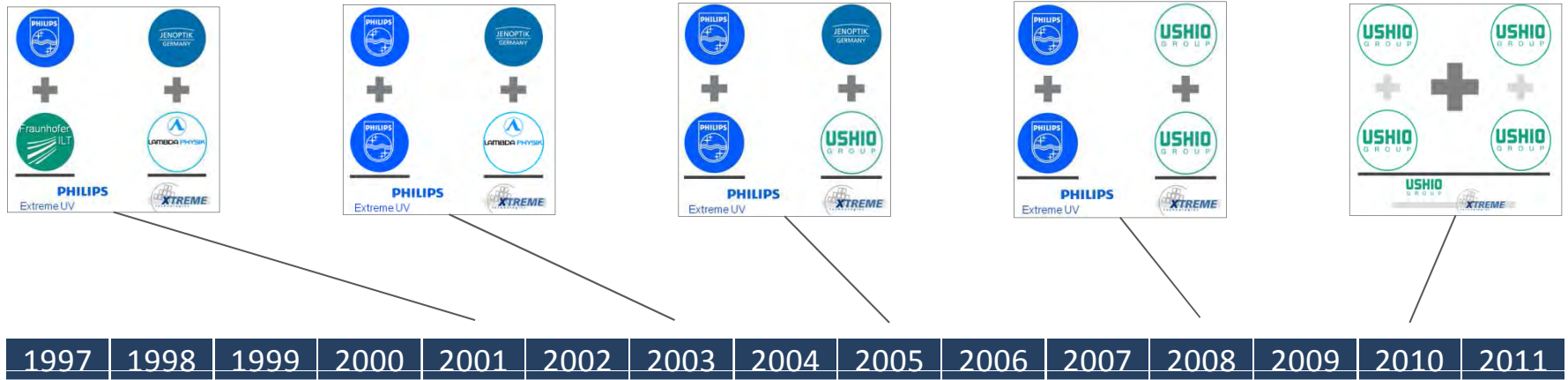

EUV: The Path To HVM

LDP Technology Status

July 2011

EUV Is Our History



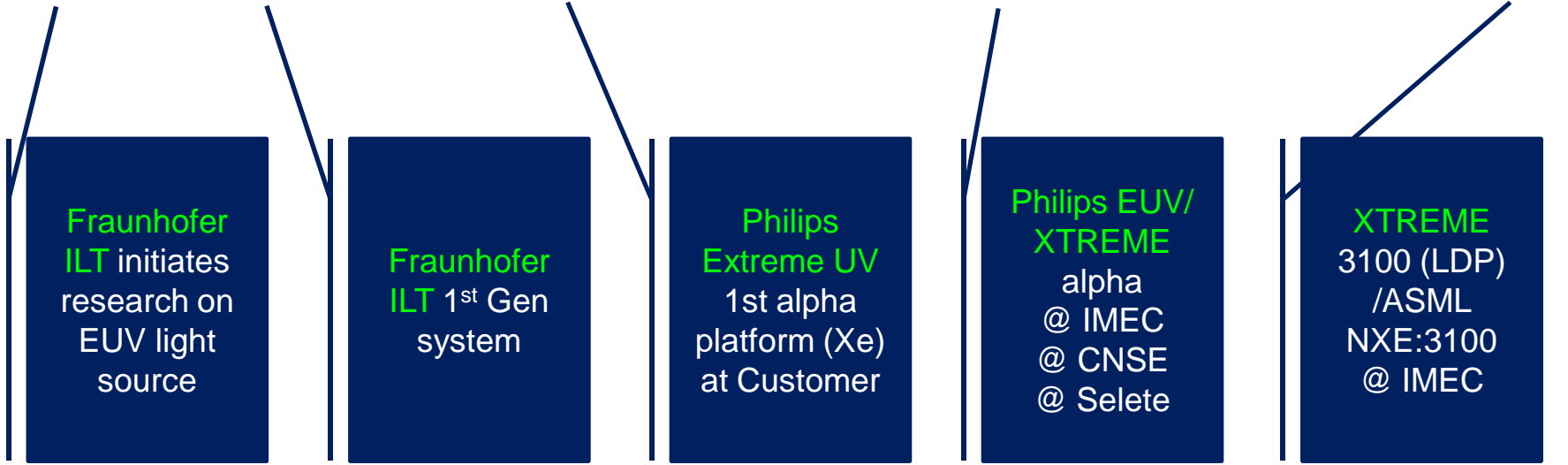
- With years of experience at LPP (Jenoptik) and DPP, XTREME has gained a deep understanding of the technological challenges

XTREME's Learning Edge

- o Enabling HVM = Reaching technology maturity BEFORE the transition to HVM



1997	1998	1999	2000	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011
------	------	------	------	------	------	------	------	------	------	------	------	------	------	------



Fraunhofer
ILT initiates
research on
EUV light
source

Fraunhofer
ILT 1st Gen
system

Philips
Extreme UV
1st alpha
platform (Xe)
at Customer

Philips EUV/
XTREME
alpha
@ IMEC
@ CNSE
@ Selete

XTREME
3100 (LDP)
/ASML
NXE:3100
@ IMEC

Enabling EUV Lithography

Requirements for an EUV Source

○ EUV SCANNER

○ Imaging

○ Yield

○ CD uniformity

○ Iso-Dense Bias

○ Maximum Throughput

○ Effective Throughput

○ EUV Source

○ Clean Photon (& Spectral purity)

○ Stability (Dose, Timing ...)

○ Power

○ Duty Cycle and Availability



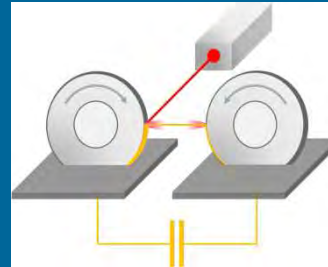
The Technology Concept: The Best Of Both Worlds

Laser-assisted Discharge Plasma

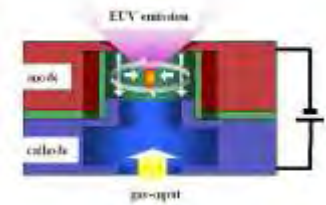
Traditional
LPP



(LDP)



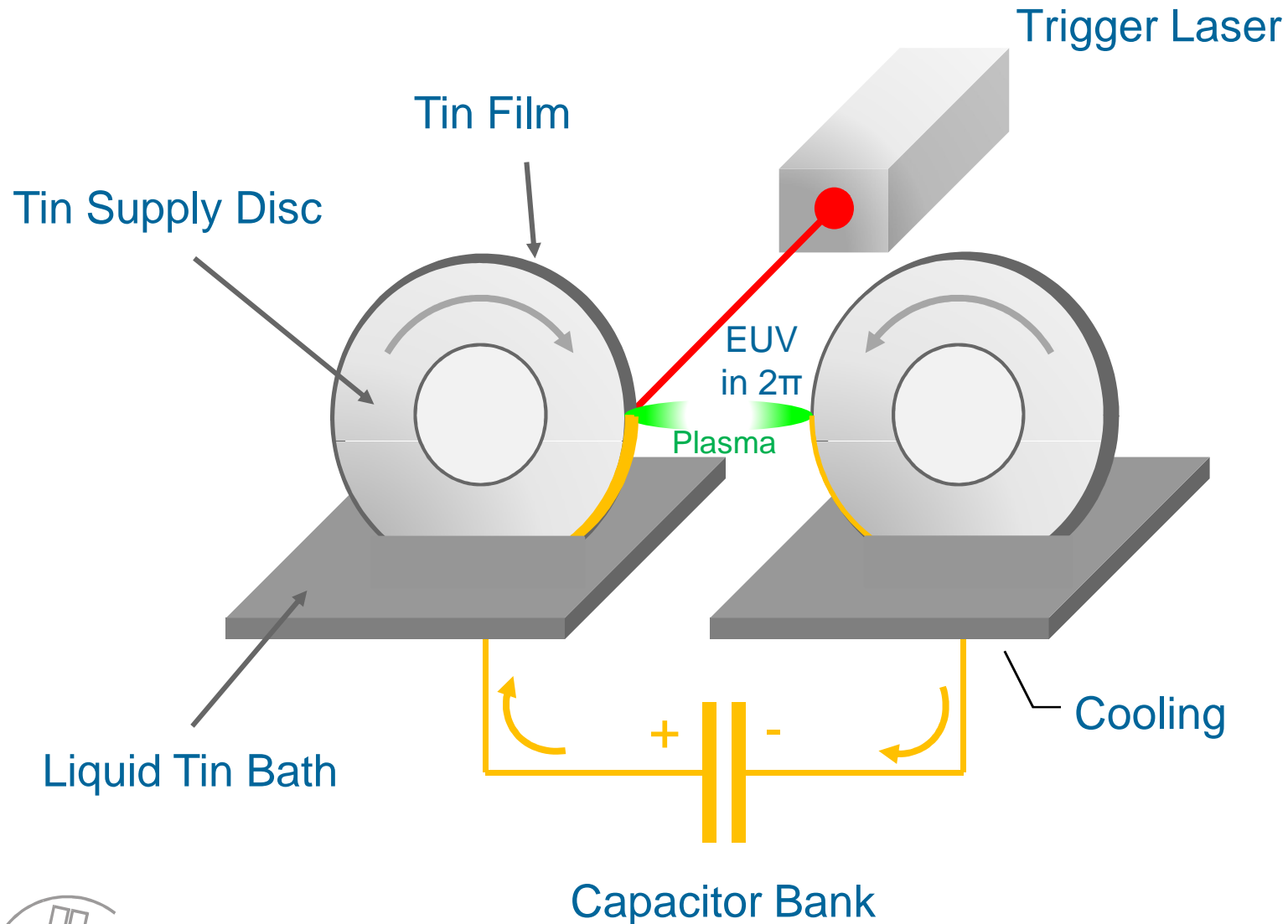
Traditional
DPP



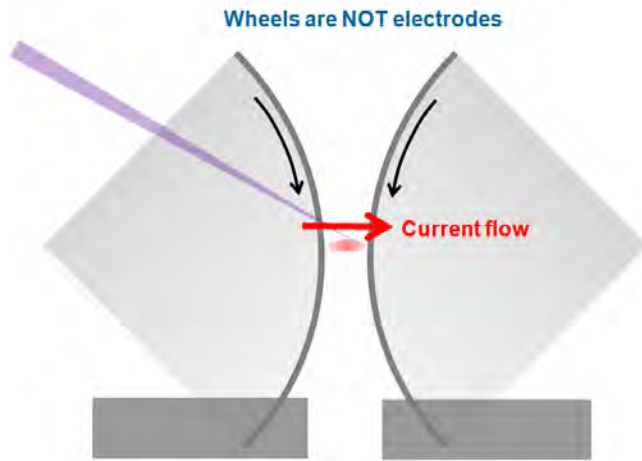
Stable

Scalable

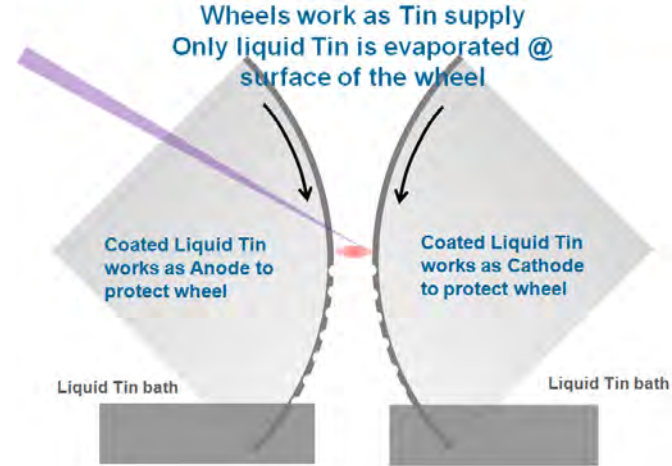
Laser-assisted Discharge Plasma (LDP) Technology Concept



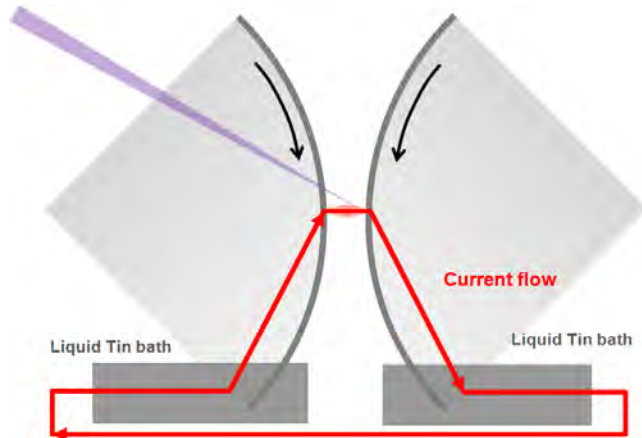
LDP Technology Concept – Tin Fulfills Multiple Roles



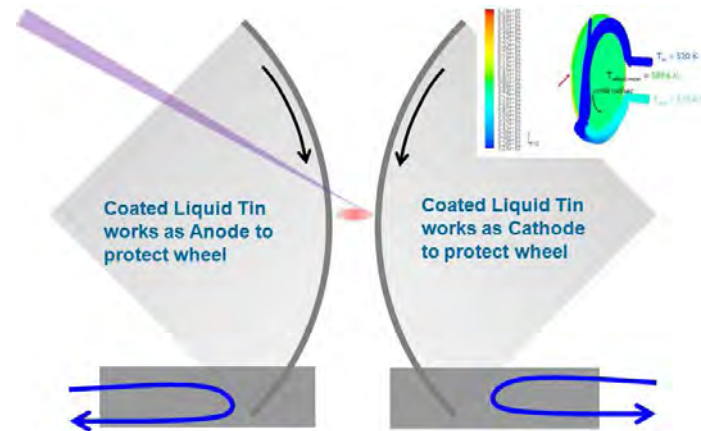
Tin as electrodes



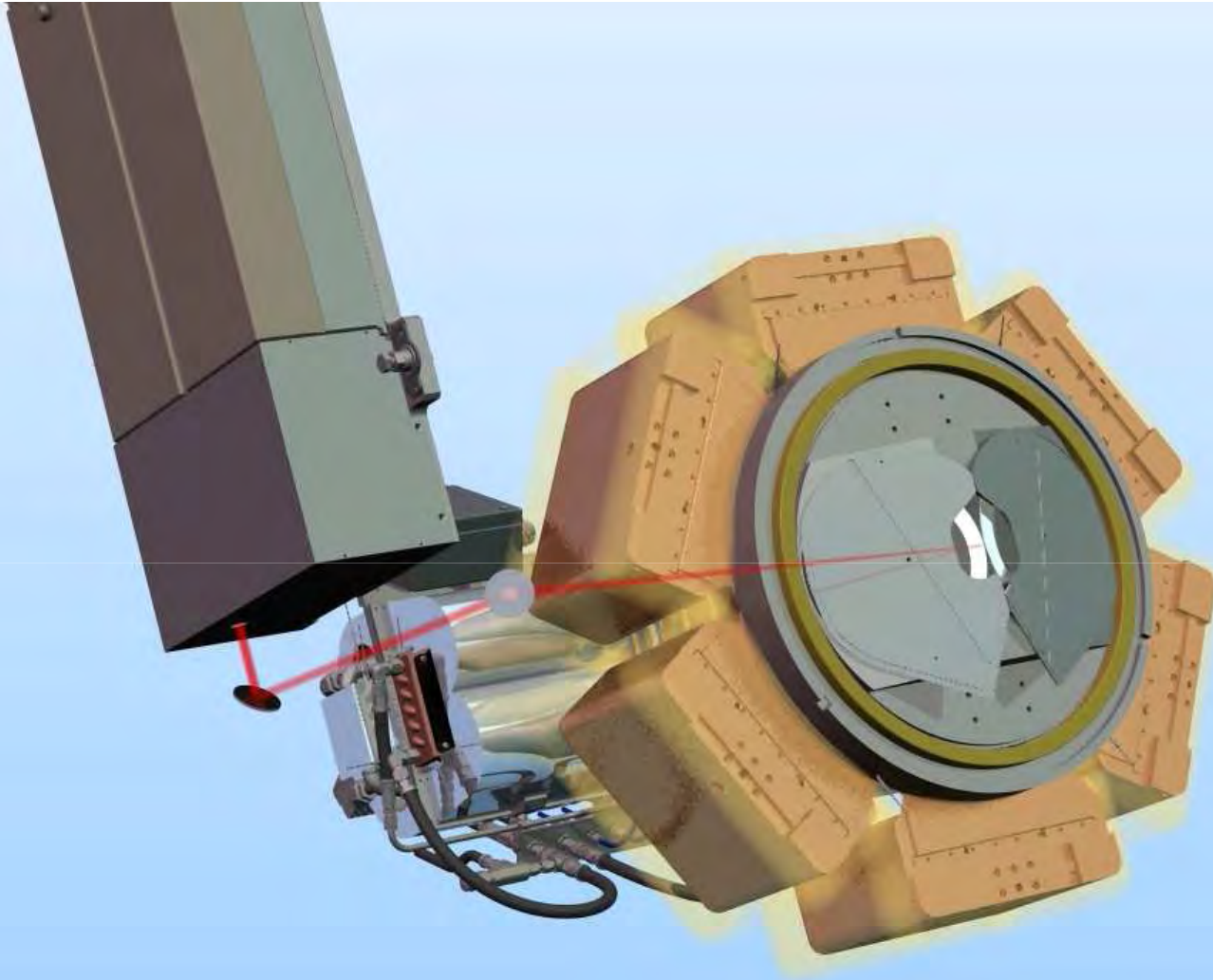
Tin as wheel protection

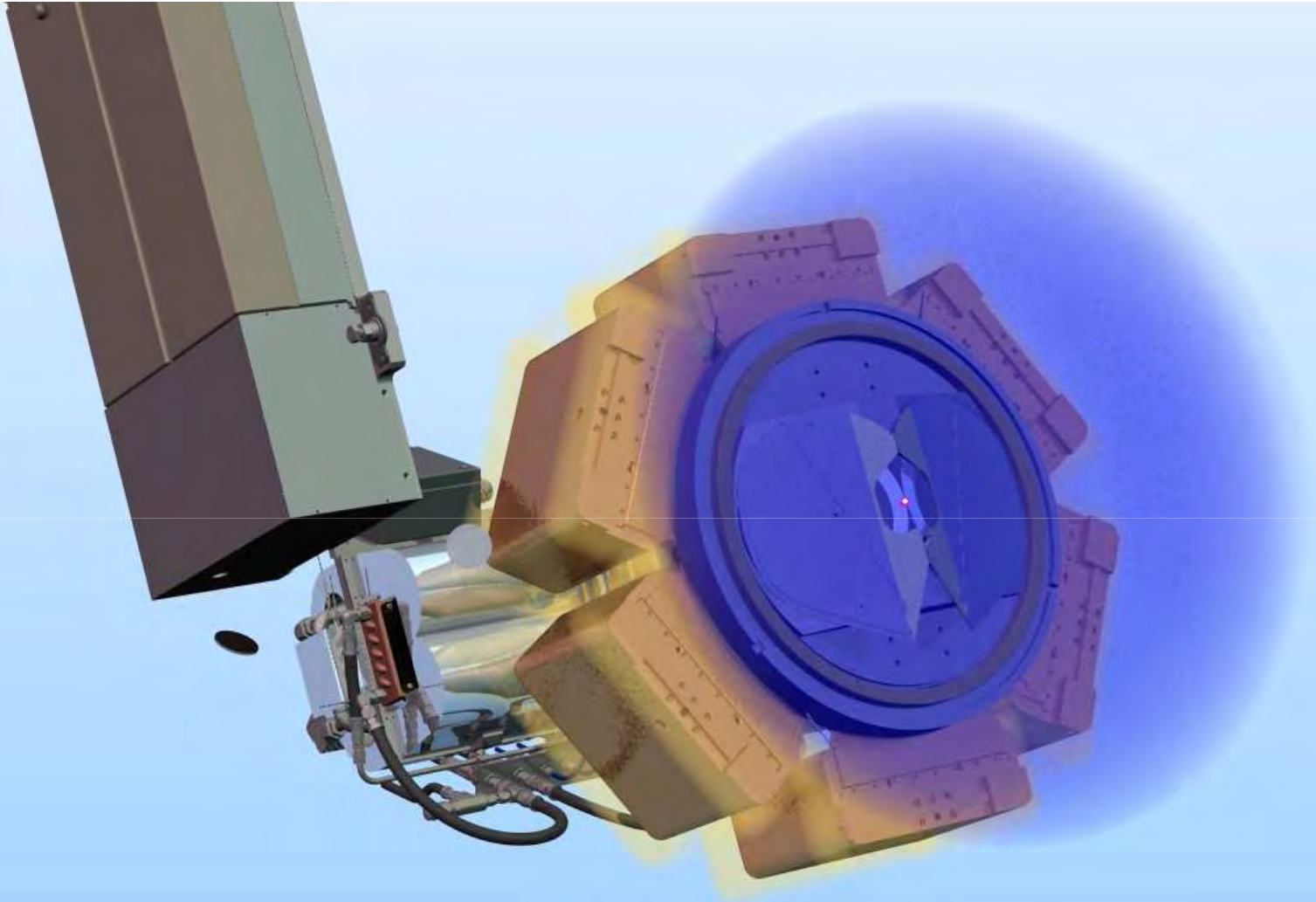


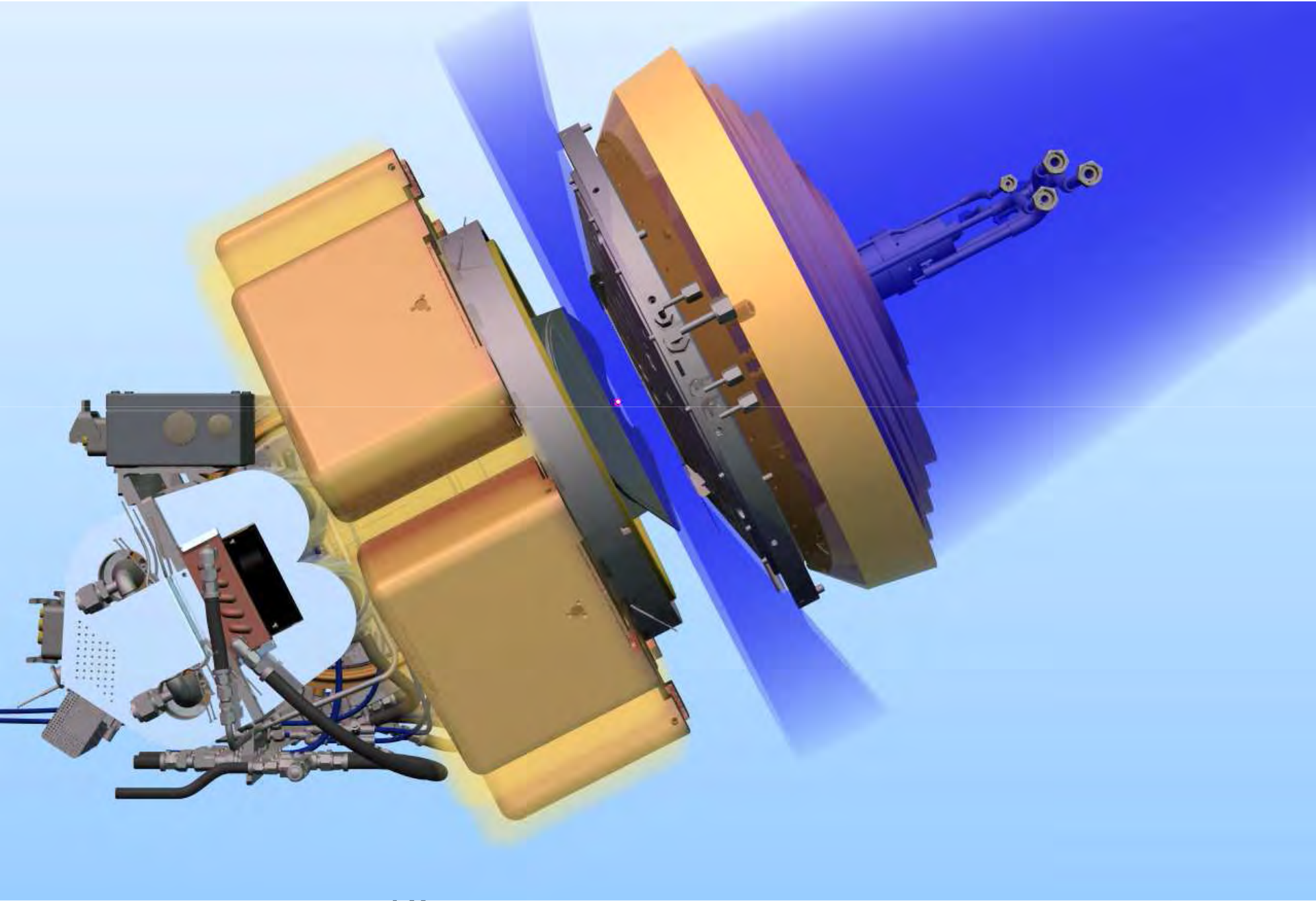
Tin as conductor

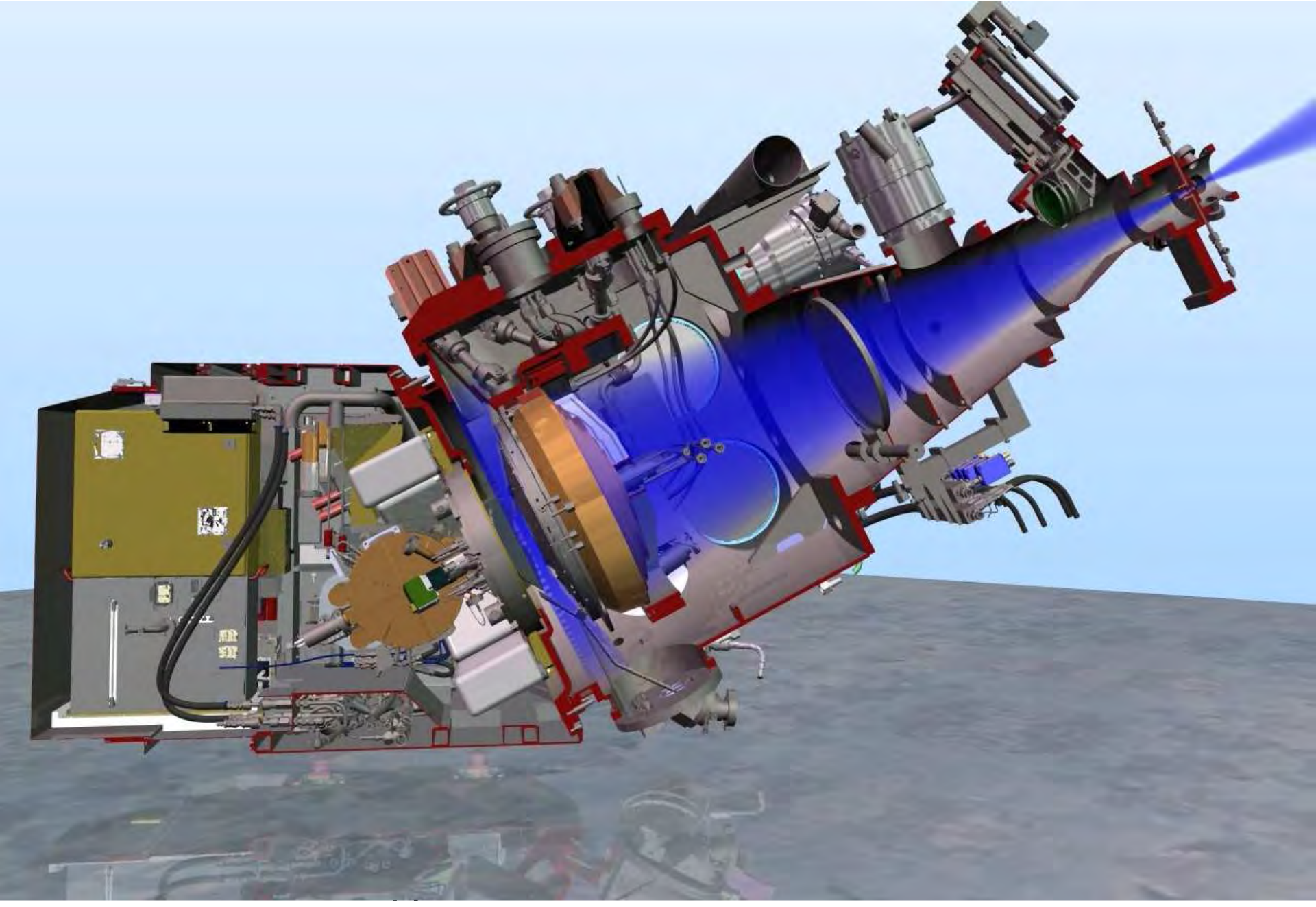


Tin as dynamic coolant

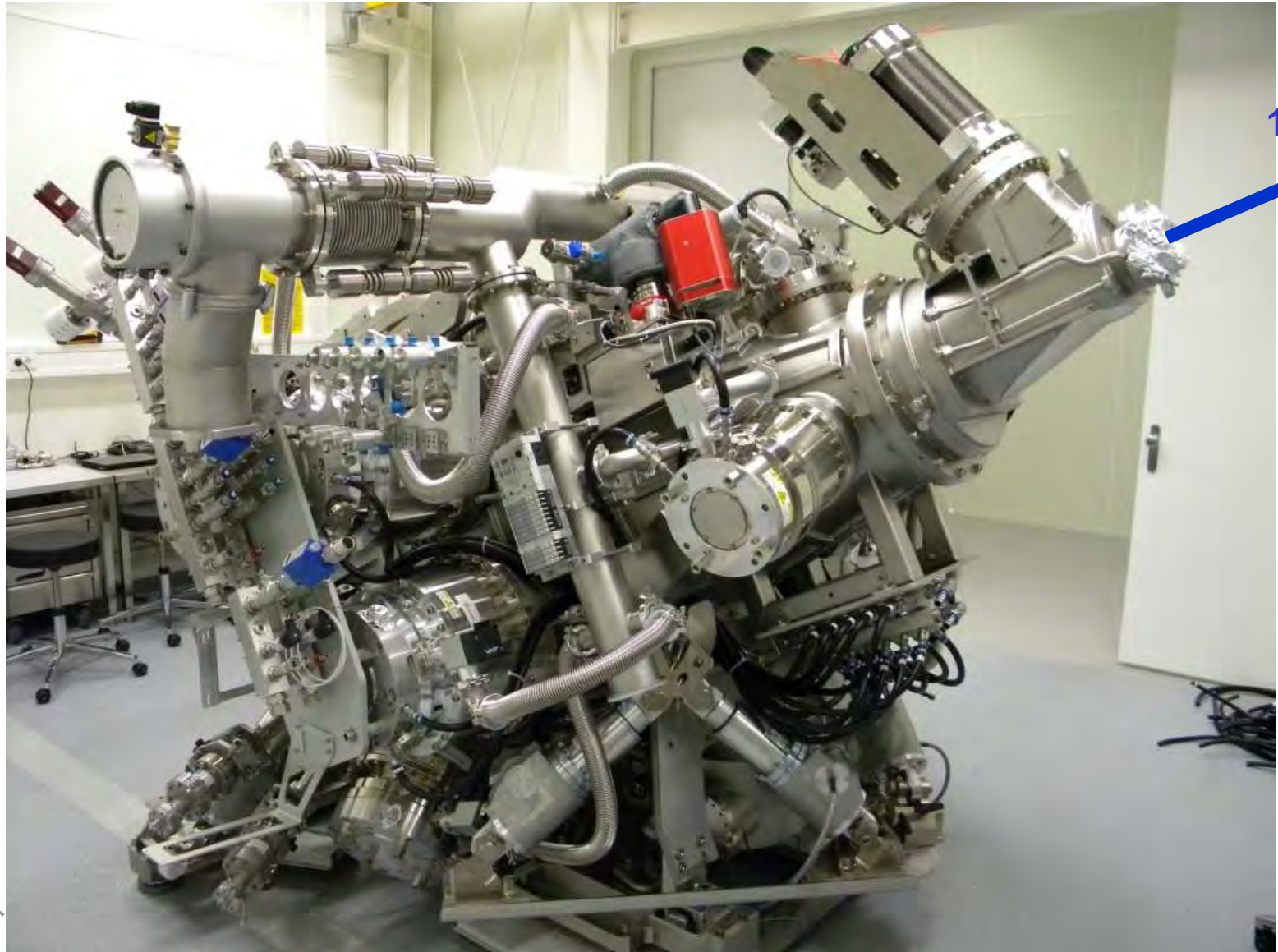




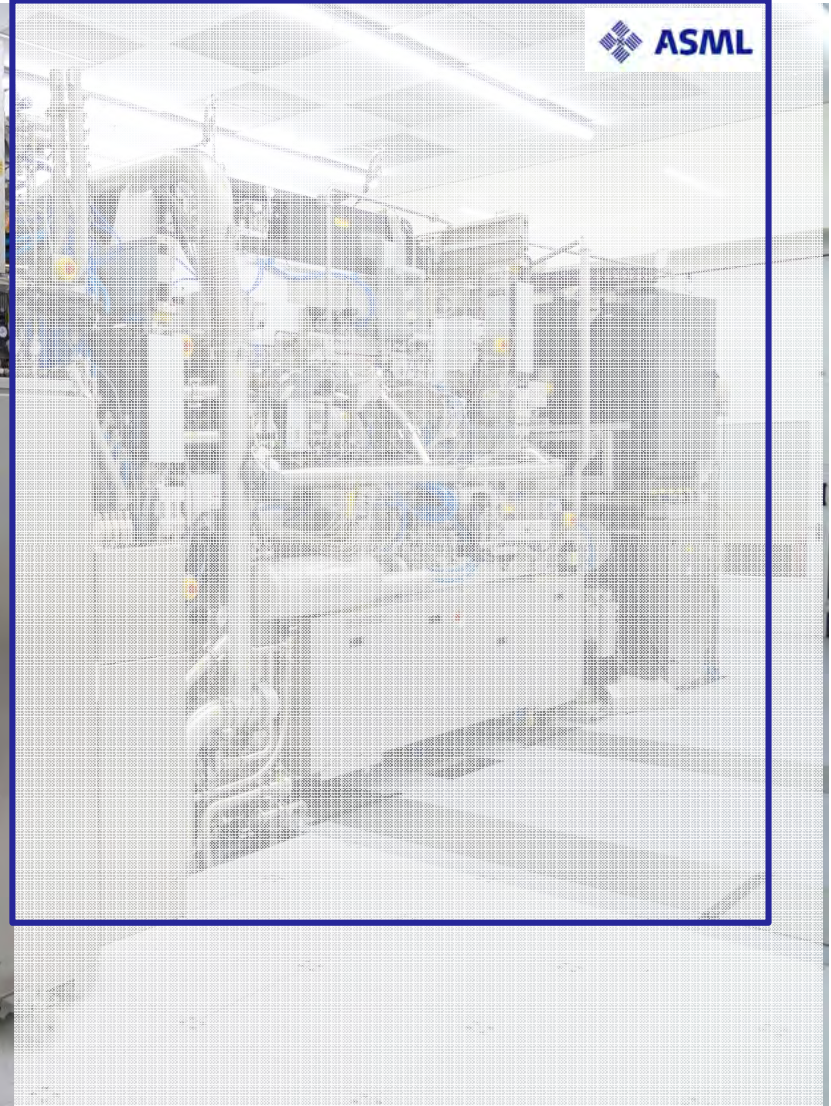
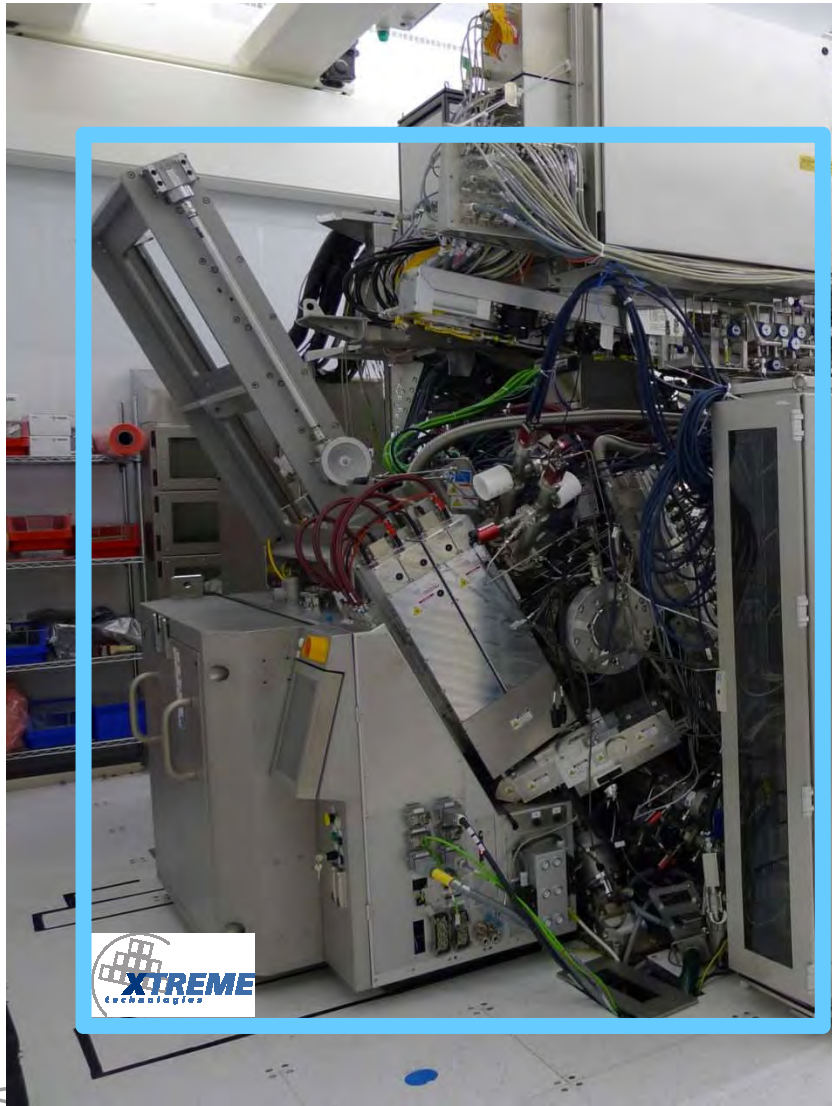




From Technology To Product



Integrated with ASML NXE:3100



Now @ IMEC



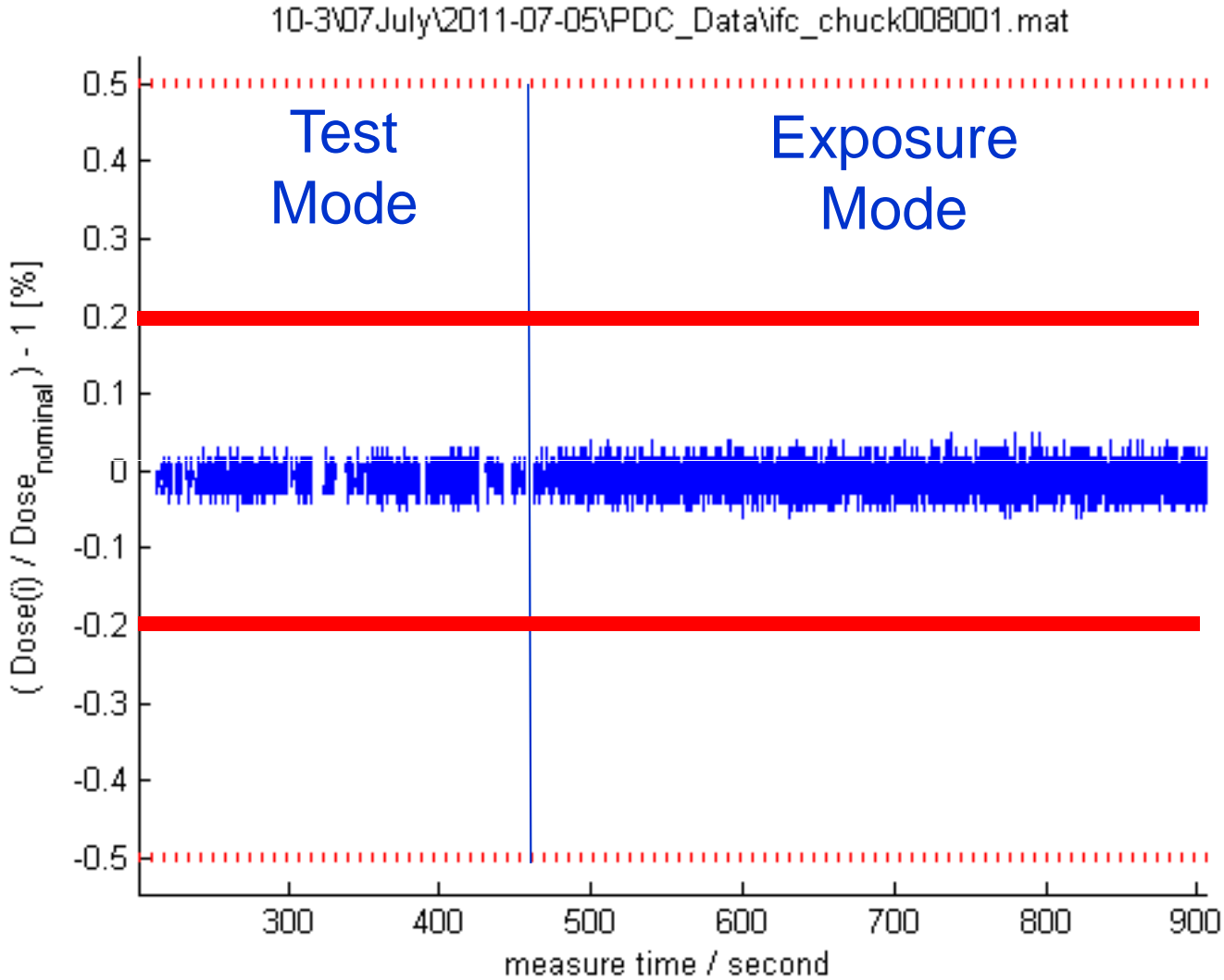
© IMEC



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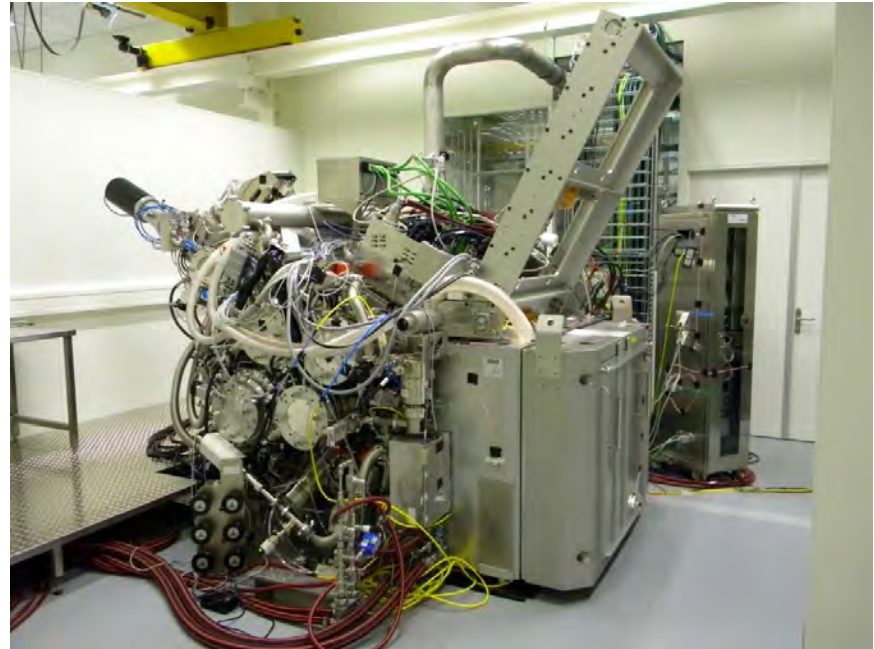
USHIO
GROUP

LDP Source Shows Good Dose Stability In Actual Operation



XTREME's Sources for NXE:3100 – Overview

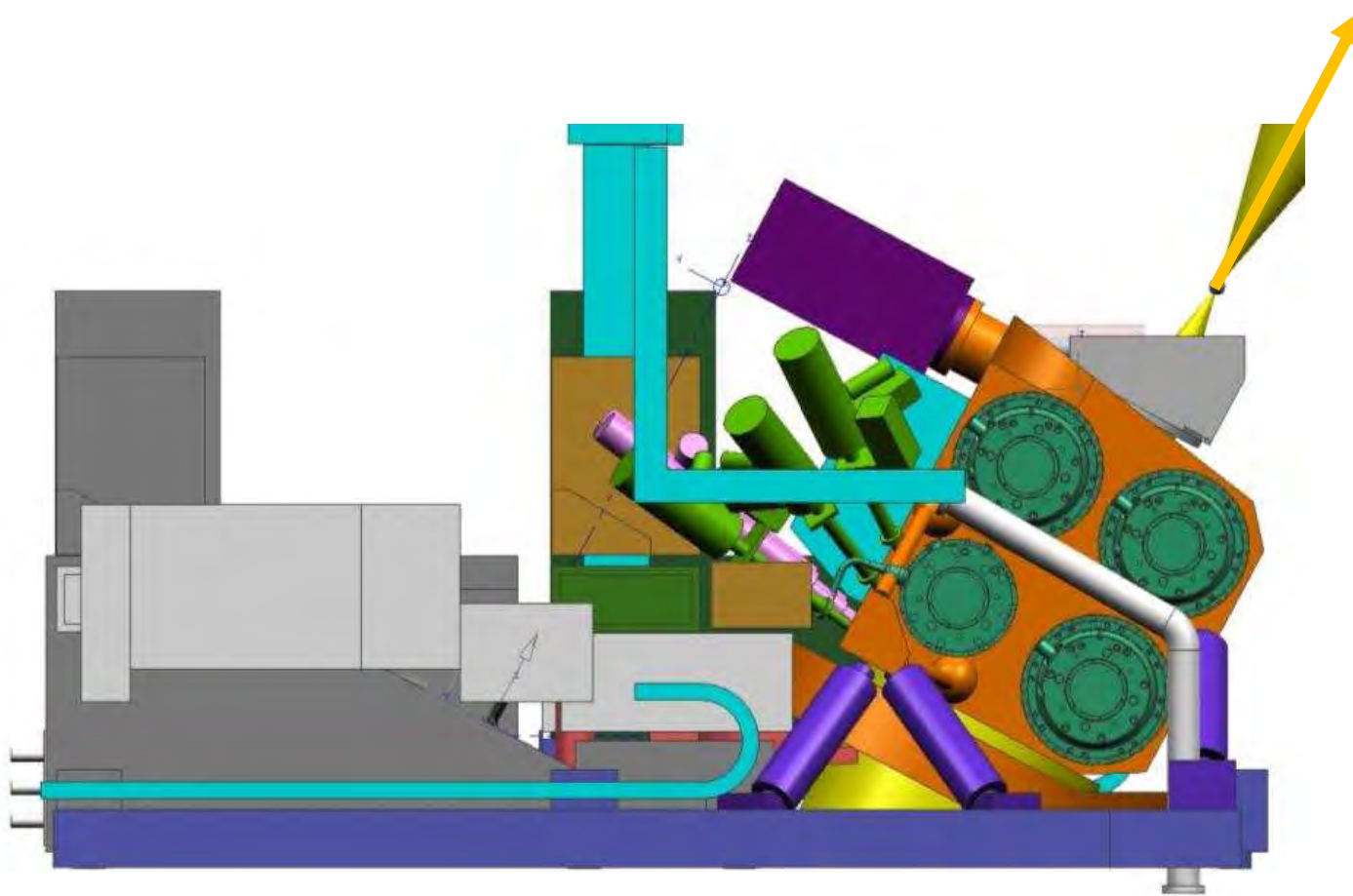
- XTREME has committed resources and multiple sources are in-house
 - 3 R&D sources (Aachen)
 - 2 product sources (Alsdorf)



- To enable EUV to transition to HVM, XTREME has also additional sources
 - For qualification x1 (Alsdorf)
 - For reliability testing x1 (Alsdorf)

Looking Forward ... HVM

- Next Gen source's architecture is finalized



Why LDP Will Be The Technology of Choice

- LDP uses **power more efficiently**
 - LDP converts wall-plug power directly into EUV plasma
- LDP is **smaller**
 - LDP architecture also takes up less space in cleanroom + subfab
- LDP keeps the lithography optics **cleaner**
 - LDP also prevents the contamination of the scanner and reticle
- LDP lithography **optics last longer**
 - LDP has proven debris mitigation technology for many years in Alpha phase

The Key Take-Aways

- **PROGRESS HAS BEEN MADE**

- XTREME's 3100 source has been installed at Imec

- **THE DIRECTION IS CLEAR**

- Power, stability, availability and predictability will converge to enable EUV to transition to HVM

- **THE CHALLENGES ARE IDENTIFIED**

- There are still challenges ahead of us
- The challenges are identified & plans have been developed
- Focus Teams are in place to address those issues

- **WE BELIEVE LDP WILL BE THE TECHNOLOGY OF CHOICE**

XTREME technologies GmbH



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